

## ALPHA FLUITIN 1532

### No CLEAN CORED SOLDER WIRE

Type: J-STD-004 – ROM1 / IPC-SF-818-M3CN / ISO 12224 – 1.1.2 / DIN 8511-F-SW26

#### DESCRIPTION

Alpha Fluitin 1532 is an activated rosin cored solder wire developed for general hand soldering applications. The unique activator system offers good thermal stability at pre-soldering temperatures ensuring that Fluitin 1532 performs extremely well on parts and surfaces which present poor or difficult soldering conditions.

Fluitin 1532 leaves post-soldering residues that are hard and which can be safely left without the need to remove them. If the removal of residues is required then semi-aqueous or aqueous systems can be used effectively.

#### FEATURES & BENEFITS

- *Minimal, non-corrosive, clear and safe residues.*
- *Very fast wetting.*
- *Good spread characteristics.*
- *Pleasant pine smell.*
- *Ease of solderability.*
- *Provides good joint appearance.*

#### APPLICATION

Fluitin 1532 is suitable for use in any commercial no-clean hand soldering application that specifies compliance to J-STD-004 – ROM1 standard.

It is suited to such areas of industry (subject to the above criteria) as TV, Audio equipment, Video/DVD, Games box and all types of household appliances.

#### HINTS & TIPS ON SOLDERING IN GENERAL

Always remember that a soldered joint is formed by heating the parts to be soldered to a temperature in excess of the melting point of the alloy to be used – in hand soldering this is how a soldering iron is used. By feeding the cored wire onto the parts, the flux is able to flow and remove oxide films, whilst the solder creates a thin intermetallic bond which becomes the solder joint.

Note the following tips:

- Use a soldering iron bit size and form to suit the operation: small bits for soldering large components may prevent the formation of a joint or slow the process down.
- Always select wire diameters to suit both soldering iron bit and the parts/components to be soldered.
- Soldering irons systems should provide sufficient heat to satisfy the requirements of the points above.
- Cored solder wires can be provided in different grades of alloy so always ensure you have selected the right grade for the application.
- Do not overheat as this causes an increase in the depth of the intermetallic layer, which in turn weakens the joint.



**Cookson Electronics** ASSEMBLY MATERIALS



The information contained herein is based on data considered accurate and is offered at no charge. No warranty is expressed or implied regarding the accuracy of this data. Liability is expressly disclaimed for any loss or injury arising out of the use of this information or the use of any materials designated.

All materials from Cookson Electronics Assembly Material are manufactured to meet the most stringent of standards and to ensure the best possible finish to every soldering application.

**TECHNICAL SPECIFICATION**

Physical Properties	Typical Values	Standard	Alloy Designation	Melting or Solidus / Liquidus Temp °C	Flux Configuration
Rosin Grade:	WW per Fed Spec. LL-R-626	ISO 9453 (1)	-Sn63Pb37	183	1.1% & 2.2%
Rosin Softening Point:	71°C (160°F)	ISO 9453 (2)	S-Sn60Pb40	183 - 190	1.1% & 2.2%
Acid Value:	170-190 (mg KOH/g)	ISO 9453 (25)	S-Sn60Pb38Cu2	183 - 190	1.1% & 2.2%
Halide Content:	0.80 – 1.10% (by weight)	ISO 9453 (30)	S-SN62Pb36Ag2	178 - 190	2.2%
Corrosiveness:	Classified to J-STD-004 as M type material	LEAD FREE	SAC 305 LEAD FREE	217	2.2% & 3.3%
Copper Mirror:	Classified to J-STD-004 as <50% breakthrough	LEAD FREE	SACX0307 LEAD FREE	217 - 228	2.2% & 3.3%
Surface Insulation Resistance: (Not Cleaned)	Passes IPC-SF-818 Class III. Test results to J-STD-004 85°C/85% RH / 7 days CD = 4.7E10 Ohms CU = 5.9E09 Ohms (Pass > 1E08 Ohms)	LEAD FREE	SAC 405	217-219	2.2% & 3.3%
		LEAD FREE	Sn99Cu1	230-240	2.2% & 3.3%
Classification:	J-STD-004 – ROM1 IPC-SF-818 – M3CN ISO 12224 – 1.1.2. Din 8511 – F – SW26				

**HEALTH & SAFETY**

Observe standard precautions for handling and use. Use in well ventilated areas. **DO NOT SMOKE.**

Alpha Fluitin 1532 wire is not considered toxic. However, its use in typical soldering applications will generate a small amount of decomposition and fumes.

These fumes **must** adequately exhausted/vented for operator safety and comfort.

The information contained herein is based on data considered accurate and is offered at no charge. No warranty is expressed or implied regarding the accuracy of this data. Liability is expressly disclaimed for any loss or injury arising out of the use of this information or the use of any materials designated.



## Cookson Electronics ASSEMBLY MATERIALS

In order to carry out your full COSHH assessment, consult the product Material Safety Data Sheet (MSDS).

---

**European Headquarters:**

Cookson Electronics Assembly Materials  
Forsyth Road, Sheerwater  
Woking, Surrey  
GU21 5RZ, United Kingdom  
Tel: +44 (0) 1483 793100  
Fax: +44 (0) 1483 793101

**Worldwide Headquarters**

Cookson Electronics Assembly Materials  
600 Route 440  
Jersey City, New Jersey 07304  
USA  
Tel: +1 (201) 434 6778  
Fax: +1 (201) 434 7508

**Regional Offices**

Belgium:	Tel: +32 (0) 14 44 50 00
France:	Tel: +33 (0) 2 41 49 00 11
Germany:	Tel: +49 (0) 2173 8490 300
Ireland:	Tel: +353 (0) 1 842 1172
Italy:	Tel: +39 (0) 2 38 33 11
Hungary:	Tel: +36 (0) 24 460 720
Netherlands:	Tel: +31 (0) 35 695 5411

[www.alphametals.com](http://www.alphametals.com)

The information contained herein is based on data considered accurate and is offered at no charge. No warranty is expressed or implied regarding the accuracy of this data. Liability is expressly disclaimed for any loss or injury arising out of the use of this information or the use of any materials designated.